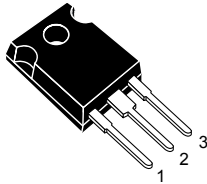
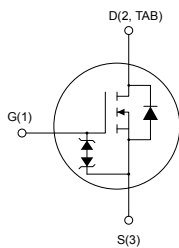


## N-channel 650 V, 51 mΩ typ., 55 A MDmesh DM6 Power MOSFET in a TO-247 package


**TO-247**


AM01476v1\_lab



### Features

Order code	$V_{DS}$	$R_{DS(on) \max}$	$I_D$
STW68N65DM6	650 V	59 mΩ	55 A

- Fast-recovery body diode
- Lower  $R_{DS(on)}$  per area vs previous generation
- Low gate charge, input capacitance and resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

### Applications

- Switching applications

### Description

This high-voltage N-channel Power MOSFET is part of the MDmesh DM6 fast-recovery diode series. Compared with the previous MDmesh fast generation, DM6 combines very low recovery charge ( $Q_{rr}$ ), recovery time ( $t_{rr}$ ) and excellent improvement in  $R_{DS(on)}$  per area with one of the most effective switching behaviors available in the market for the most demanding high-efficiency bridge topologies and ZVS phase-shift converters.

#### Product status link

[STW68N65DM6](#)

#### Product summary

<b>Order code</b>	STW68N65DM6
<b>Marking</b>	68N65DM6
<b>Package</b>	TO-247
<b>Packing</b>	Tube

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D$	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	55	A
$I_D$	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	35	A
$I_{DM}^{(1)}$	Drain current (pulsed)	172	A
$P_{TOT}$	Total power dissipation at $T_C = 25\text{ }^\circ\text{C}$	431	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	100	V/ns
$di/dt^{(2)}$	Peak diode recovery current slope	1000	A/ $\mu\text{s}$
$dv/dt^{(3)}$	MOSFET $dv/dt$ ruggedness	100	V/ns
$T_{STG}$	Storage temperature range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating junction temperature range		$^\circ\text{C}$

1. Pulse width limited by safe operating area.
2.  $I_{SD} \leq 55\text{ A}$ ,  $V_{DS}(\text{peak}) < V_{(BR)DSS}$ ,  $V_{DD} = 400\text{ V}$ .
3.  $V_{DS} \leq 520\text{ V}$ .

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance, junction-to-case	0.29	$^\circ\text{C/W}$
$R_{thJA}$	Thermal resistance, junction-to-ambient	50	$^\circ\text{C/W}$

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
$I_{AR}$	Avalanche current, repetitive or not repetitive ( $t_p$ limited by $T_J$ max)	9	A
$E_{AS}$	Single pulse avalanche energy (starting $T_J = 25\text{ }^\circ\text{C}$ , $I_D = I_{AR}$ , $V_{DD} = 50\text{ V}$ )	930	mJ

## 2 Electrical characteristics

$T_C = 25\text{ °C}$  unless otherwise specified

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}$ , $I_D = 1\text{ mA}$	650			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$ , $V_{DS} = 650\text{ V}$			1	$\mu\text{A}$
		$V_{GS} = 0\text{ V}$ , $V_{DS} = 650\text{ V}$ , $T_C = 125\text{ °C}^{(1)}$			100	
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 25\text{ V}$			$\pm 5$	$\mu\text{A}$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	3.25	4.00	4.75	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}$ , $I_D = 24\text{ A}$		51	59	m $\Omega$

1. Defined by design, not subject to production test.

**Table 5. Dynamic characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0\text{ V}$	-	3528	-	pF
$C_{oss}$	Output capacitance		-	258	-	pF
$C_{rSS}$	Reverse transfer capacitance		-	1.5	-	pF
$C_{oss\ eq}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0\text{ to }520\text{ V}$ , $V_{GS} = 0\text{ V}$	-	609	-	pF
$R_G$	Intrinsic gate resistance	$f = 1\text{ MHz}$ , $I_D = 0\text{ A}$	-	1.25	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 520\text{ V}$ , $I_D = 48\text{ A}$ , $V_{GS} = 0\text{ to }10\text{ V}$ (see Figure 14. Test circuit for gate charge behavior)	-	80	-	nC
$Q_{gs}$	Gate-source charge		-	21.5	-	nC
$Q_{gd}$	Gate-drain charge		-	35	-	nC

1.  $C_{oss\ eq}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 325\text{ V}$ , $I_D = 34\text{ A}$ , $R_G = 4.7\text{ }\Omega$ , $V_{GS} = 10\text{ V}$	-	25	-	ns
$t_r$	Rise time		-	32	-	ns
$t_{d(off)}$	Turn-off delay time	(see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	76	-	ns
$t_f$	Fall time		-	9	-	ns

**Table 7. Source-drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		55	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		172	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0\text{ V}$ , $I_{SD} = 48\text{ A}$	-		0.98	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 48\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ ,	-	135		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60\text{ V}$	-	0.641		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	9.5		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 48\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ ,	-	245		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 60\text{ V}$ , $T_J = 150\text{ }^\circ\text{C}$	-	2.45		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	(see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	20		A

1. Pulse width is limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

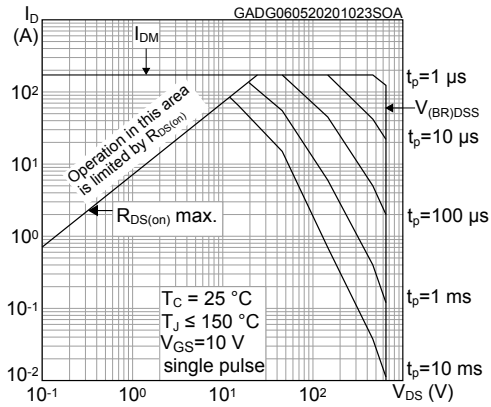


Figure 2. Maximum transient thermal impedance

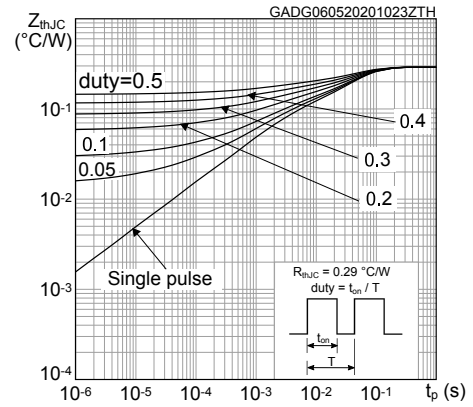


Figure 3. Typical output characteristics

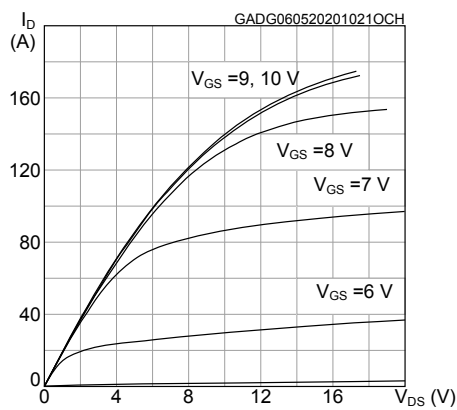


Figure 4. Typical transfer characteristics

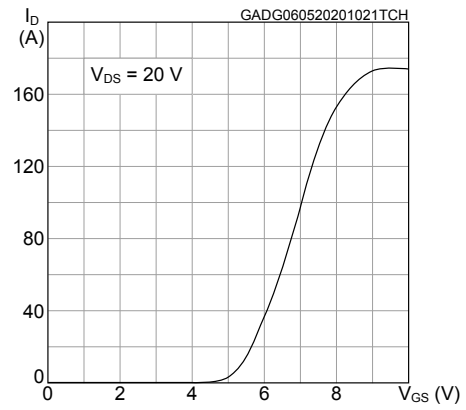


Figure 5. Typical gate charge characteristics

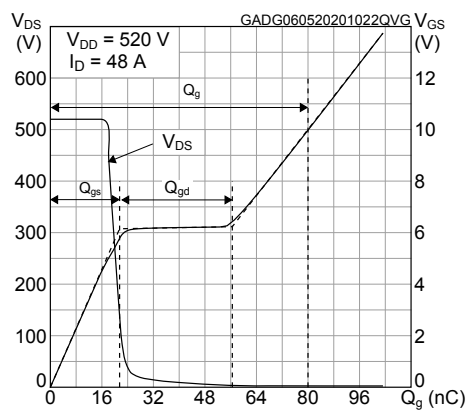
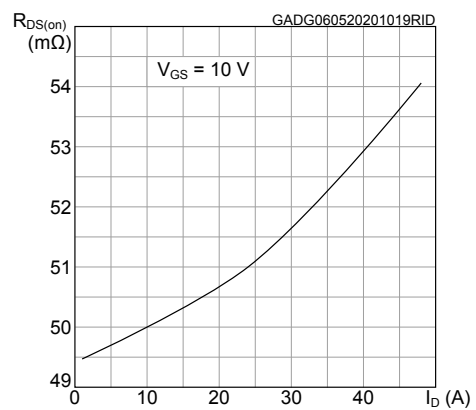
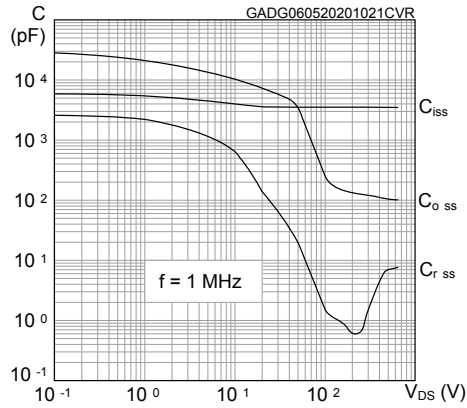


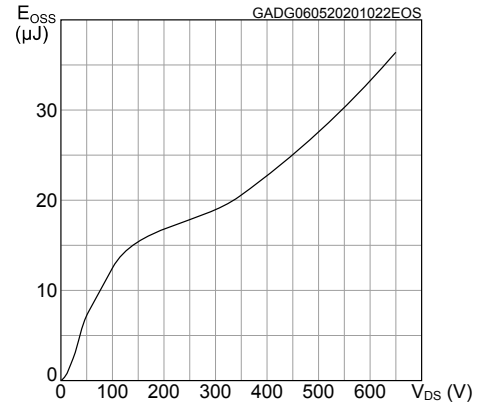
Figure 6. Typical drain-source on-resistance



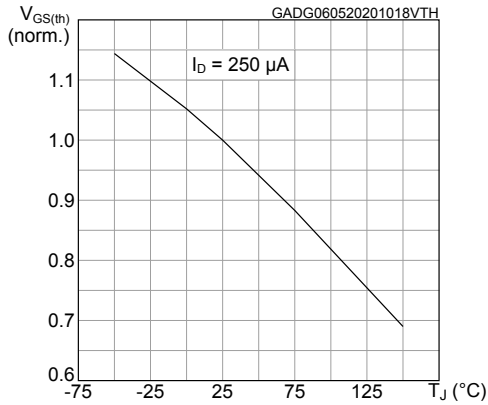
**Figure 7. Typical capacitance characteristics**



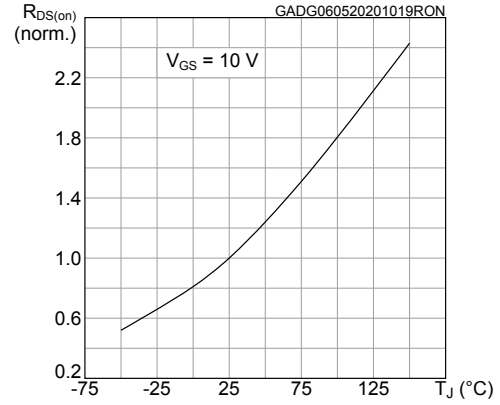
**Figure 8. Typical output capacitance stored energy**



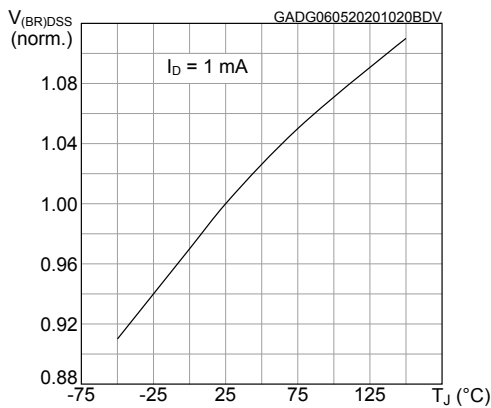
**Figure 9. Normalized gate threshold vs temperature**



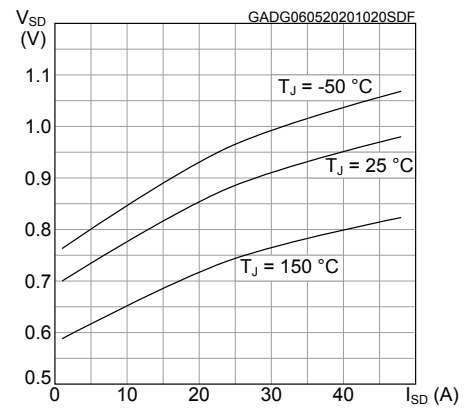
**Figure 10. Normalized on-resistance vs. temperature**



**Figure 11. Normalized breakdown voltage vs temperature**

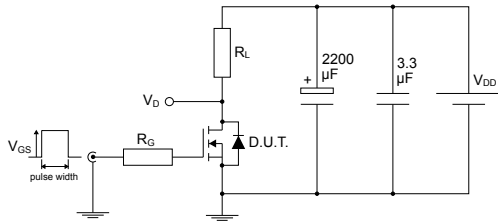


**Figure 12. Typical reverse diode forward characteristics**



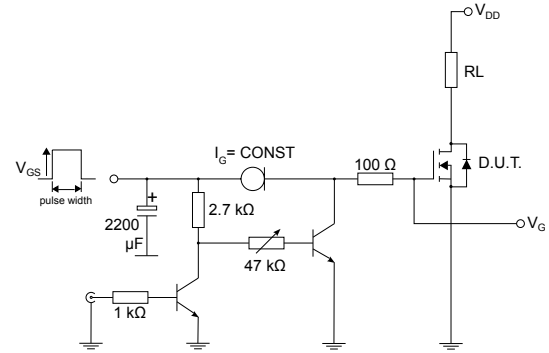
### 3 Test circuits

Figure 13. Test circuit for resistive load switching times



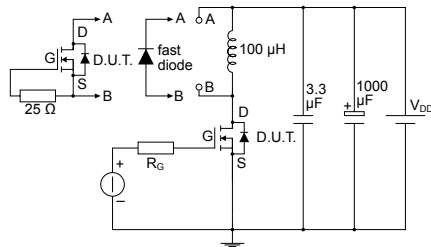
AM01468v1

Figure 14. Test circuit for gate charge behavior



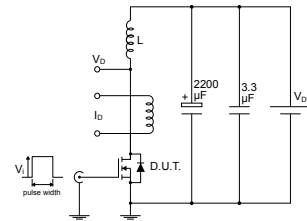
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Figure 15. Test circuit for inductive load switching and diode recovery times



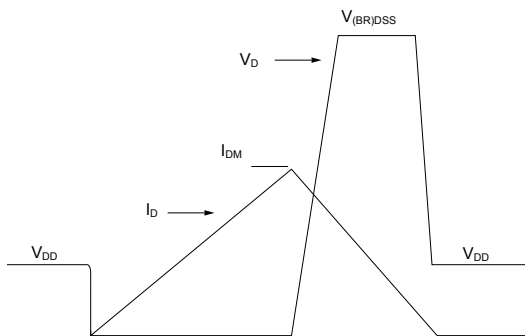
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Figure 16. Unclamped inductive load test circuit



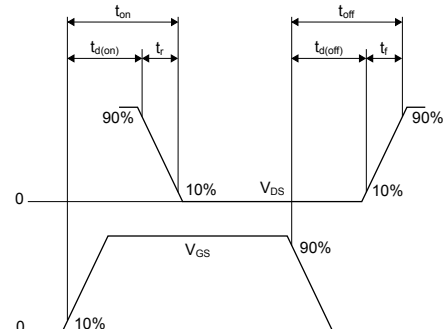
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Figure 17. Unclamped inductive waveform



AM01472v1

Figure 18. Switching time waveform



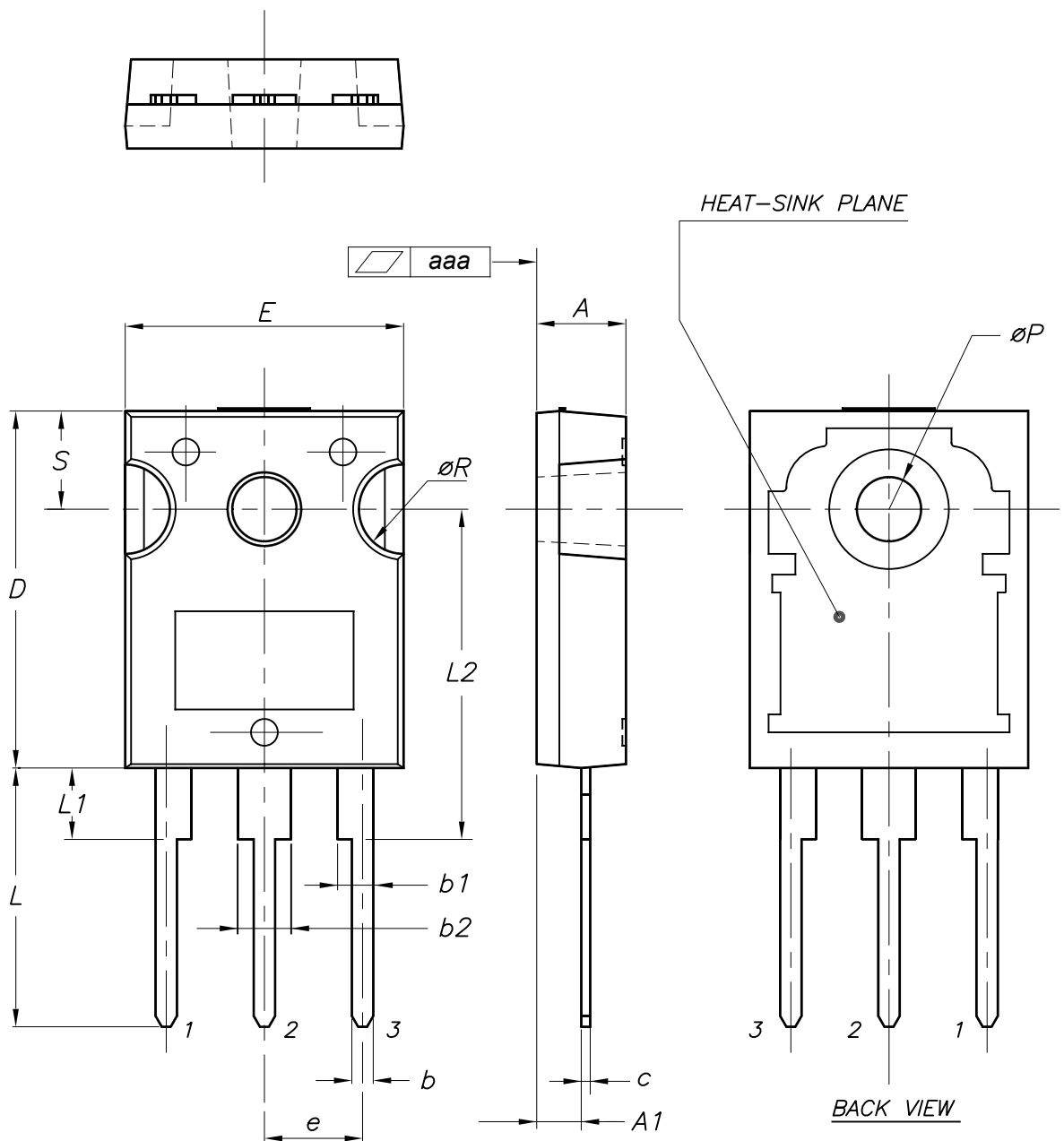
AM01473v1

## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 TO-247 package information

Figure 19. TO-247 package outline



0075325\_10



**Table 8. TO-247 package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70
aaa		0.04	0.10

## Revision history

**Table 9. Document revision history**

Date	Version	Changes
08-May-2020	1	First release. Part number previously included in datasheet DS12367.
25-Mar-2021	2	Updated <i>Table 4. On/off states</i> . Updated <i>Section 4 Package information</i> . Minor text changes.
21-May-2021	3	Modified <i>Table 1. Absolute maximum ratings</i> , <i>Table 2. Thermal data</i> and <i>Table 7. Source-drain diode</i> . Modified <i>Figure 1. Safe operating area</i> and <i>Figure 2. Maximum transient thermal impedance</i> . Minor text changes.

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